

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6413037

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOSHIHARU MORI	08/07/2020
MASAKI KUSANO	08/07/2020
DAISUKE MATSUURA	08/07/2020
DAISUKE KOBAYASHI	08/03/2020
KAZUYUKI HIROSE	08/03/2020
OSAMU KAWASAKI	08/03/2020
RECEIVING PARTY DATA	
Name:	MITSUBISHI HEAVY INDUSTRIES, LTD.
Street Address:	2-3, MARUNOUCHI 3-CHOME
City:	CHIYODA-KU, TOKYO
State/Country:	JAPAN
Postal Code:	100-8332
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17057428
CORRESPONDENCE DATA	
Fax Number:	(202)721-8250
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2027218200
Email:	wlp@wenderoth.com
Correspondent Name:	WENDEROTH, LIND & PONACK, L.L.P.
Address Line 1:	1025 CONNECTICUT AVENUE NW
Address Line 2:	SUITE 500
Address Line 4:	WASHINGTON, D.C. 20036
ATTORNEY DOCKET NUMBER:	2020-2099A
NAME OF SUBMITTER:	KAREN GASS
SIGNATURE:	/KAREN GASS/
DATE SIGNED:	11/20/2020

Total Attachments: 12

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**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN
APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)
AND ASSIGNMENT**

Title of Invention	APPARATUS FOR COMPENSATING FOR RADIATION RESISTANCE OF SEMICONDUCTOR MEMORY, METHOD THEREFOR, AND ELECTRONIC CIRCUIT
-------------------------------	--

As the below named inventor, I hereby declare that:

This declaration

is directed to:

☐

The attached application, or

☒

United States application or PCT international application
number PCT/JP2019/040152 filed on October 11, 2019

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: "A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56."

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid, I hereby sell and assign to

MITSUBISHI HEAVY INDUSTRIES, LTD.

(Name of Assignee)

of 2-3, Marunouchi 3-Chome, Chiyoda-ku, Tokyo, 100-8332, Japan

(address of Assignee)

(hereinafter designated as the Assignee) my entire right, title and interest for the United States as defined in 35 USC 100, for any invention set forth in the above-identified application.

I agree to execute all papers necessary in connection with this application for patent in the USPTO for the invention, and any continuation, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

I agree to execute all papers necessary in connection with any post-grant proceeding which may occur in connection with this application or continuation, divisional or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such post-grant proceeding.

I agree to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

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I hereby authorize and request the USPTO to issue any and all Letters Patents of the United States resulting from the application or any continuation, divisional or reissue applications thereof to the Assignee, as Assignee of my entire interest, and covenant that I have not executed, and will not execute, any agreement in conflict herewith.

I hereby grant the firm of Wenderoth Lind & Ponack, L.L.P., the power to insert on this document any further identification which may be necessary or desirable.

Inventor (Legal Name): Yoshiharu MORI

Signature: Yoshiharu Mori

Date: August 7, 2020

Witness (Optional) _____

Witness (Optional) _____

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Inventor (Legal Name): Masaki KUSANO

Signature: Masaki Kusano

Date: August 7, 2020

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Inventor (Legal Name): Daisuke MATSUURA

Signature: Daisuke Matsuura

Date: August 7, 2020

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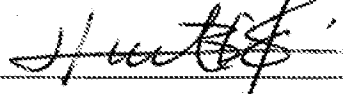
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Inventor (Legal Name): Daisuke KOBAYASHI

Signature: 

Date: August 3, 2020

Witness (Optional) _____

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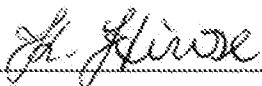
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Inventor (Legal Name): Kazuyuki HIROSE

Signature: 

Date: August 3, 2020

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Inventor (Legal Name): Osamu KAWASAKI

Signature: Osamu Kawasaki

Date: August 3, 2020

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